EUROSOI "Who is Who" Guide

Name of the organisation	
Organization Legal name:	**Institiut für Mikroelektronik und Mechatronik Systeme gGmbH**
Organization short name:	IMMS gGmbH
Internet homepage:	**www.imms.de**

Contact person				
Name:	*Nuernbergk*		*Title:*	*Dr.-Ing.*
First name:	*Dirk*		*Sex:*	*M*
Phone:	*0049/361/6632520*	*E-mail:*	*dirk.nuernbergk@imms.de*	
Postal Address	*Konrad-Zuse-Strasse 14*			

Other Senior Researchers: (up to 10 names, please include e-mail address)
Dipl.-Ing Stefan Bormann, stefan.bormann@imms.de
Dipl.-Ing. Sonja Richter, sonja.richter@imms.de
Dr.-Ing. Valentin Nakov, valentin.nakov@imms.de

Experience and expertise fields: (50 words)
Modelling of circuit elements of a partially depleted SOI technology,
Analogue and digital circuit design of high temperature SOI circuits. Realised and measured circuits 10Bit ADC, DAC, Bandgap reference, voltage regulators, comparators, OpAmps (Analogue Library). HT-camshaft sensor, HT pressure sensor interface, SOI EEPROM circuit and cell design, SRAM,

Facilities and Equipment:
- Wafer prober with bridge, pulse measurement units, ICCAP for device measurements and modelling,
- digital tester HP82000, thermo stream (T=-70..225°C), digital data analyser, spectrum analyser, network thermo chuck (T=-40..225°C), HP4155, low leakage switch matrix, LCR measurement analyser
- RF measurements equipment up to 50 GHz, high frequency noise measurements, on wafer characterisation (8 inch wafer)

Low frequency noise measurement equipment, on wafer characterisation (8 inch wafer)

Three last international research projects:

TERMIS - High temperature/ High-Voltage Mixed-Signal SOI ASICs for Aerospace Applications – ESPRIT: 29'598 (European commission) -
ATHIS - Advanced Techniques for High Temperature System-On-Chip - GRD1-2001-40707 **(European commission)**